

TOSHIBA Photo-IC Silicon Epitaxial Planar

TPS853

Mobile Phones, PHS
 Notebook PCs, PDAs
 Video cameras, Digital Still Cameras
 Other Equipment Requiring Luminosity Adjustment

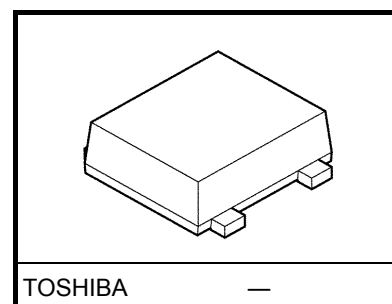
The TPS853 is an ultra-compact surface-mount photo-IC for illuminance sensors which incorporates a photodiode and current amp circuit in a single chip.

The sensitivity is superior to that of a phototransistor, and exhibits little variation.

It has spectral sensitivity closer to luminous efficiency and excellent output linearity.

This photo-IC can be used as the power-saving control for domestic appliances or for backlighting for displays in cellular phones.

This device includes stand-by function which can reduce the power consumption of the system.



Weight: 0.0054 g (typ.)

- Ultra-compact and light surface-mount package: $2.0 \times 2.1 \times 0.7$ mm
- Excellent output linearity of illuminance
- Little fluctuation in light current and high level of sensitivity
 - : $I_L = 37 \mu\text{A}$ to $74 \mu\text{A}$ @EV = 100 lx using fluorescent light
 - : Light current variation width: $\times 1.67$ (when light current classification is specified.)
 - : Little temperature fluctuation in light current
- Built-in luminous-efficiency correction function, reduced sensitivity variations due to various light sources
 - : I_L (using incandescent light)/ I_L (using fluorescent light) = 1.2 (typ.)
- Low supply voltage, making device suitable for battery-powered equipment: $V_{CC} = 2.2$ V to 5.5 V
- Lead(Pb)-Free

Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Supply voltage	V_{CC}	-0.5 to 7	V
Output voltage	V_{OUT}	$\leq V_{CC}$	V
Stand-by voltage	V_{stb}	$\leq V_{CC}$	V
Light current	I_L	5	mA
Permissible power dissipation	P	35	mW
Operating temperature range	T_{opr}	-30 to 85	°C
Storage temperature range	T_{stg}	-40 to 100	°C
Soldering temperature range (Note 1)	T_{sol}	260	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: The reflow time and the recommended temperature profile are shown in the section entitled Handling Precautions.

Operating Ranges

Characteristics	Symbol	Min	Typ.	Max	Unit
Supply voltage	V_{CC}	2.2	—	5.5	V
Stand-by voltage	V_{stb}	2.2	—	V_{CC}	V

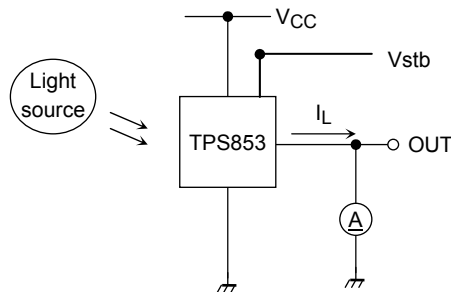
Electrical and Optical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Supply voltage	V _{CC}	—	2.2	—	5.5	ϕ
Supply current (1)	I _{CC} +I _{stb} (1) (Note 6)	V _{CC} = 3 V, V _{stb} = 3 V, E _V = 1000 lx R _L = 1 kΩ (Note 2)	—	624	—	μA
Supply current (2)	I _{CC} +I _{stb} (2) (Note 6)	V _{CC} = 3 V, V _{stb} = 0.3 V, E _V = 1000 lx R _L = 1 kΩ (Note 2)	—	4.2	—	μA
Light current (1)	I _L (1)	V _{CC} = 3 V, V _{stb} = 3 V, E _V = 100 lx (Note 2), (Note 4)	—	62	—	μA
Light current (2)	I _L (2)	V _{CC} = 3 V, V _{stb} = 3 V, E _V = 10 lx (Note 3), (Note 4)	3.7	5.2	7.4	μA
Light current (3)	I _L (3)	V _{CC} = 3 V, V _{stb} = 3 V, E _V = 100 lx (Note 3), (Note 4)	37	52	74	μA
Light current ratio	$\frac{I_L (1)}{I_L (3)}$	—	—	1.2	1.7	
Dark current	I _{LEAK}	V _{CC} = 3.3 V, V _{stb} = 3.3V, E _V = 0	—	—	0.1	μA
Saturation output voltage	V _O	V _{CC} = 3 V, V _{stb} = 3 V, R _L = 150 kΩ, E _V = 100 lx (Note 3)	2.2	2.35	—	V
Peak sensitivity wavelength	λ _p	—	—	600	—	nm
Switching time	Rise time	V _{CC} = 3 V, V _{stb} = 3 V, R _L = 5 kΩ (Note 5)	—	0.07	1	ms
	Fall time		—	0.4	2	

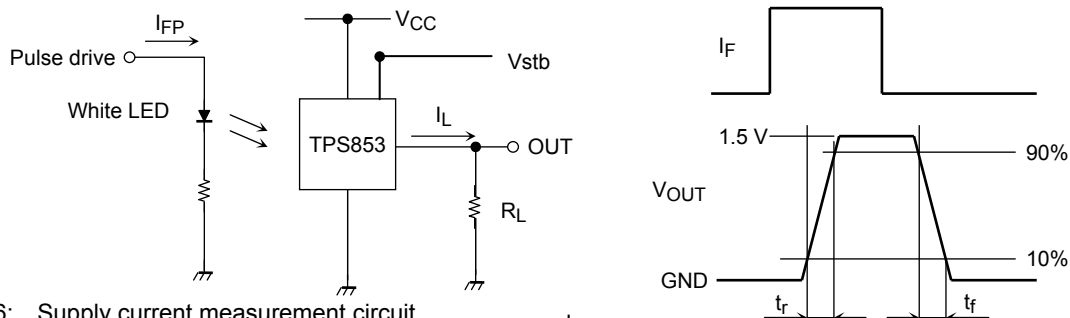
Note 2: CIE standard A light source is used (color temperature = 2856K, approximated incandescence light).

Note 3: Fluorescence light is used as light source. However, white LED is substituted in a mass-production process.
I_L classification I_L (3) → A: 39 μA to 65 μA

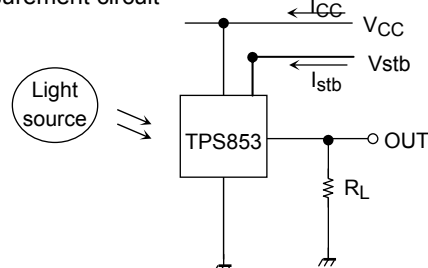
Note 4: Light current measurement circuit



Note 5: Rise time/fall time time measurement method




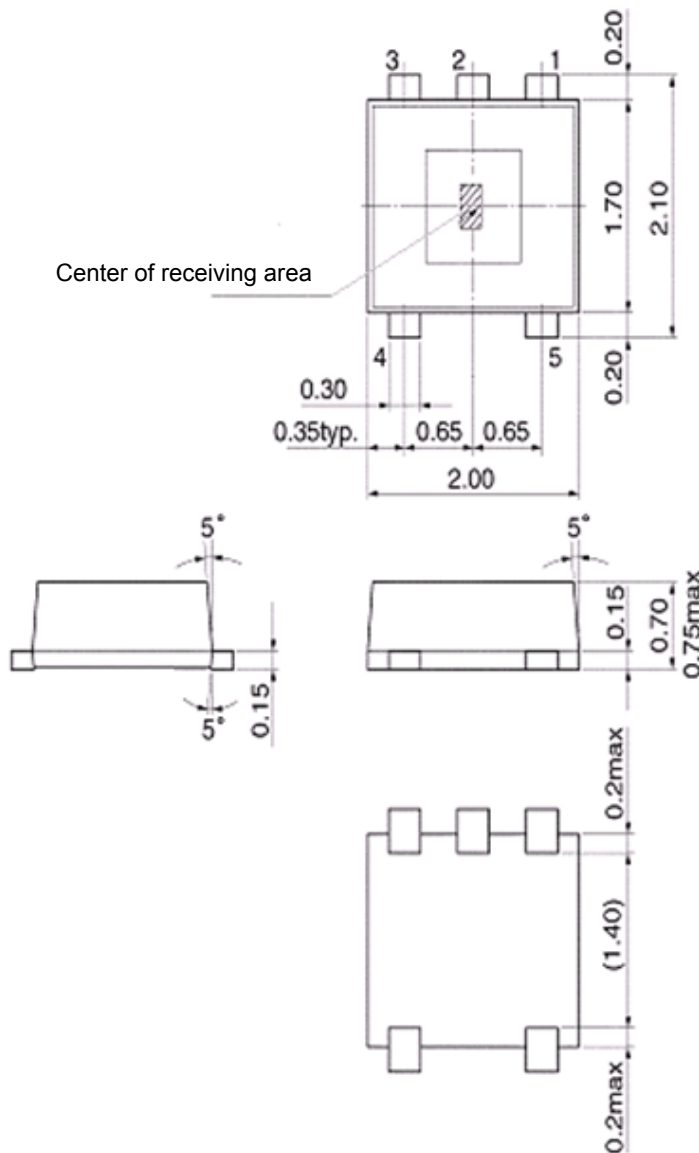
Note 6: Supply current measurement circuit



Package Dimensions

Unit: mm
 Tolerance: ± 0.1
 (): Reference value

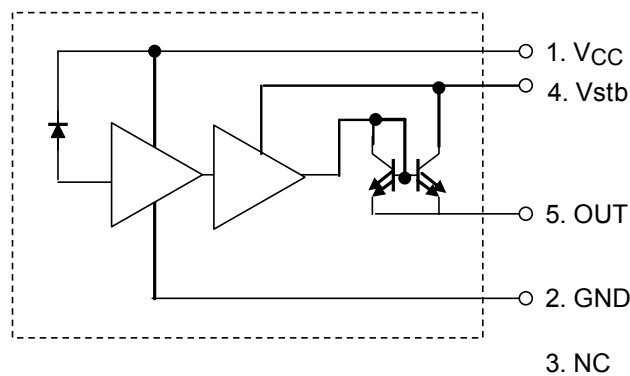
 : Light-receiving area
 Size of light-receiving area:
 (0.51x0.13 mm)



- Pin connection
1. V_{CC}
 2. GND
 3. NC
 4. V_{stb}
 5. OUT

Weight: 0.0054 g (typ.)

Block Diagram



Handling Precautions

Insert a bypass condenser of up to 0.1μF between Vcc and GND near the device to stabilize the power supply line. When Vcc is turned on it takes at least 100 ms for the internal circuit to stabilize. During this time the output signal is unstable. Please do not use the unstable signal as the output signal.

Moisture-Proof Packing

- (1) To avoid moisture absorption by the resin, the product is packed in an aluminum envelope with silica gel.
- (2) Since the optical characteristics of the device can be affected during soldering by vaporization resulting from prior absorption of moisture and they should therefore be stored under the following conditions:
 Temperature: 5°C to 30°C, Relative humidity: 70% (max), Time: 168 h (max)
- (3) Baking is required if the devices have been store unopened for more than six months or if the aluminum envelope has been opened for more than 168 h.
 These devices are packed on tapes; hence, please avoid baking at high temperature.
 Recommended baking conditions: 60°C for 12 h or longer

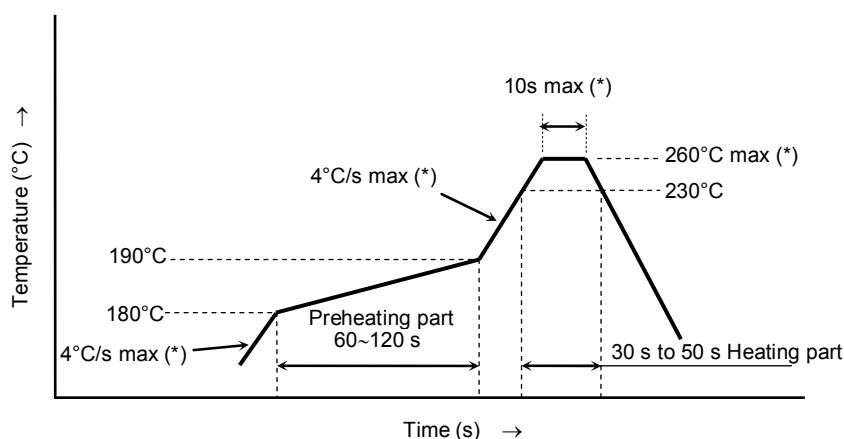
Mounting Precautions

TPS853 uses a clear resin, and delicate handling is necessary for it. The characteristic change or the product might be damaged by the handling method of mounting. Please note the following and handle the product.

- (1) Do not apply stress to the resin at high temperature.
 Time until the product returns at the normal temperature after mounting of the reflow is different according to the mounting substrate and the environment.
 Please do not give the stress with heat remained in the product.
- (2) The resin part is easily scratched, so avoid friction with hard materials.
- (3) When installing the assembly board in equipment, ensure that this product does not come into contact with other components.
- (4) Please confirm the heat contraction of the substrate of the reflow mounting doesn't influence the product. The load is given to the product by mounting that the heat contraction is large on the substrate and the installation position of the substrate. Please note that the characteristic changes or the product might be damaged.

Mounting Methods

- (1) Example of reflow soldering

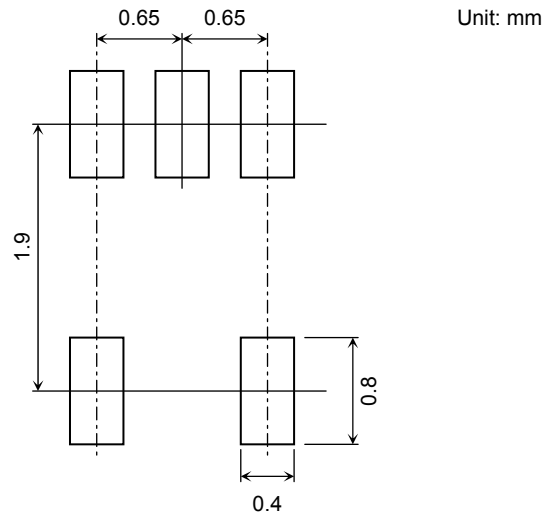


(*)The product is evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than MAX values) as an evaluation. Please perform reflow soldering under the above conditions. Perform reflow soldering no more than twice.

- Please perform the first reflow soldering within 168 h after opening the package with reference to the above temperature profile.

- Second reflow soldering
 In case of second reflow soldering, it should be performed within 168 h after first reflow under the above conditions.
 Storage conditions before second reflow soldering: 30°C, 70% RH or lower
- Do not perform flow soldering.
- Make any necessary soldering correction manually.
 (do not do this more than once for any given pin.)
 Temperature: no more than 350°C (25 W for soldering iron)
 Time: within 5 s

(2) Recommended soldering pattern



(3) Cleaning conditions

- When cleaning is required after soldering
 - Chemicals: AK225 alcohol
 - Temperature and time: 50°C × 30 s or 30°C × 3 minutes
 - Ultrasonic cleaning: 300 W or less

Packing Specification

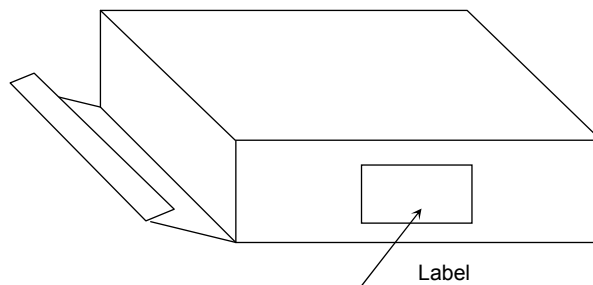
(1) Packing quantity

Reel (minimum packing quantity)	3,000 devices
Carton	5 reels (15,000 devices)

(2) Packing format

- An aluminum envelope containing silica gel and reels is deaerated and sealed.
- Pack shock-absorbent materials around the aluminum envelopes in the cartons to cushion them.

- Carton specification

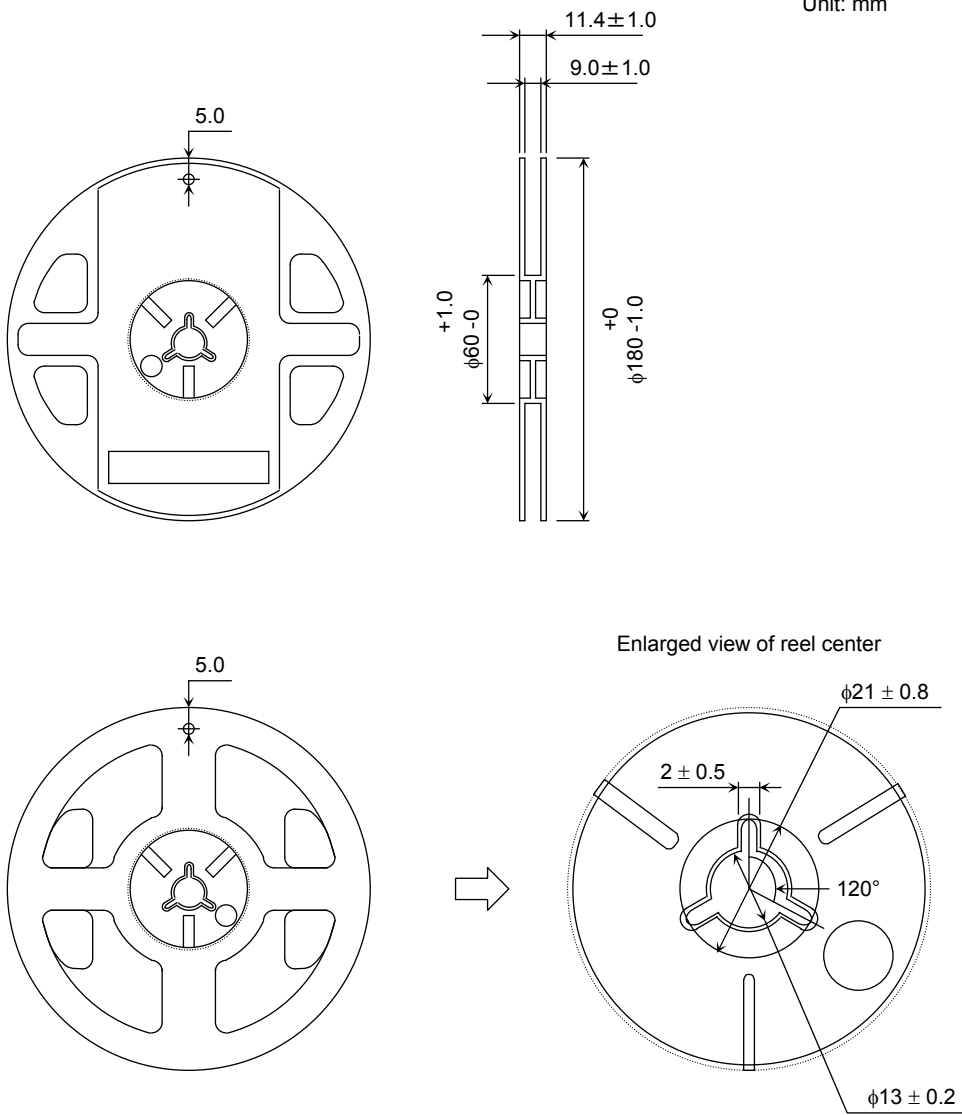


Carton dimensions
 (W) 81 mm × (L) 280 mm × (H) 280 mm

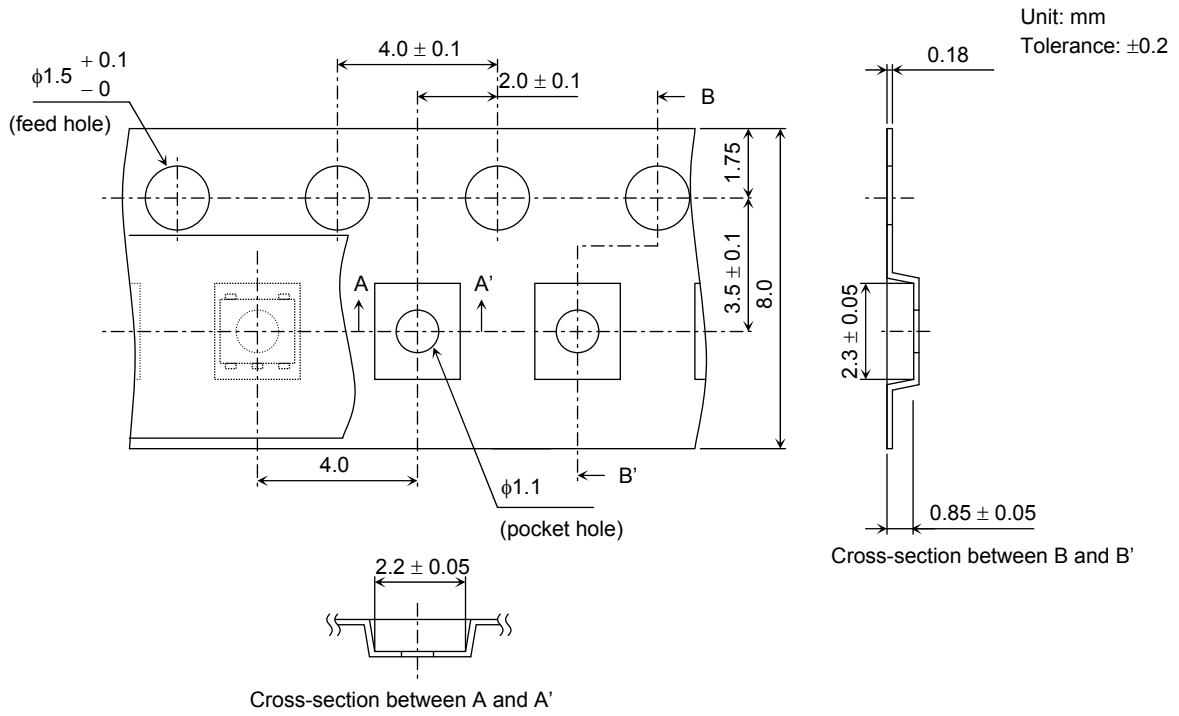
Tape Packing Specifications

- (1) Reel dimensions
Reel material: Plastic

Unit: mm



(2) Tape dimensions
Tape material: Plastic (anti-electrostatic)

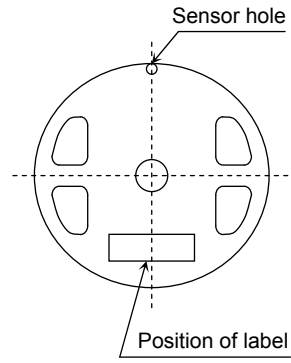


Reel Label

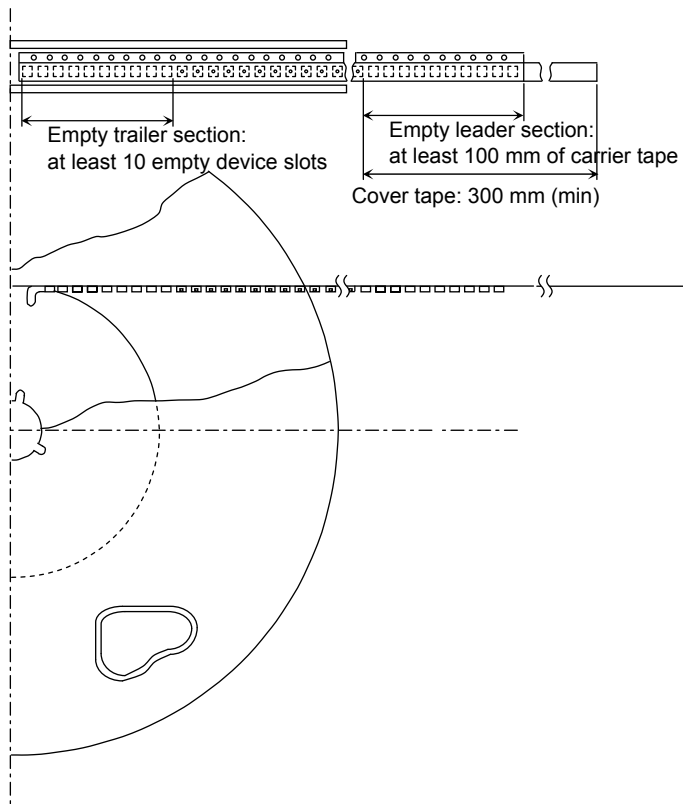
The label markings may include product number, tape type and quantity.

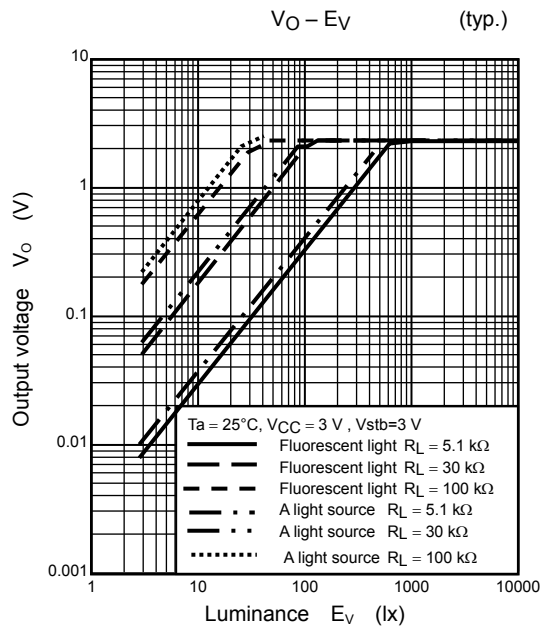
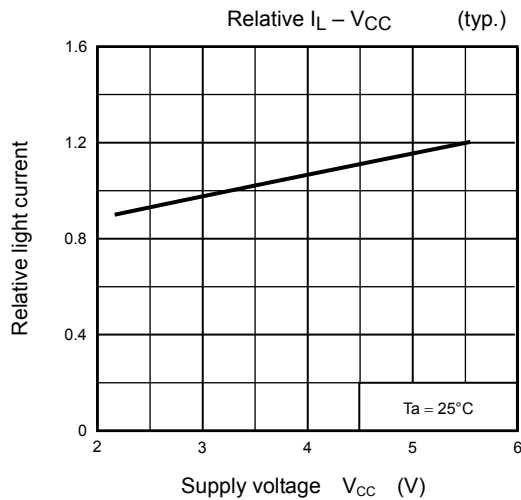
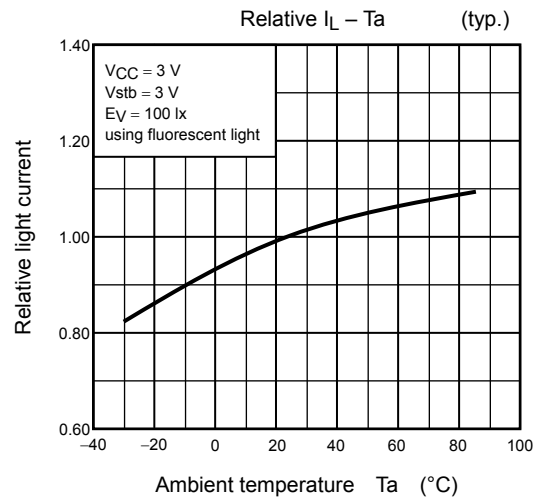
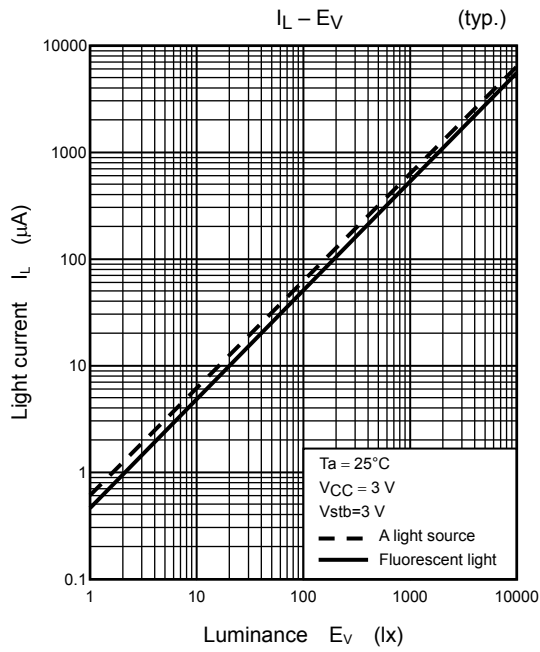
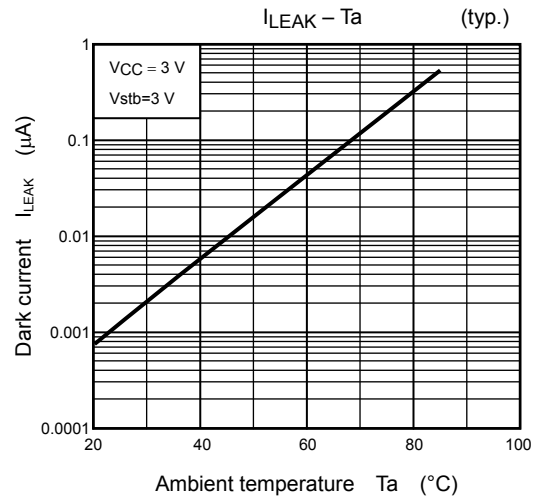
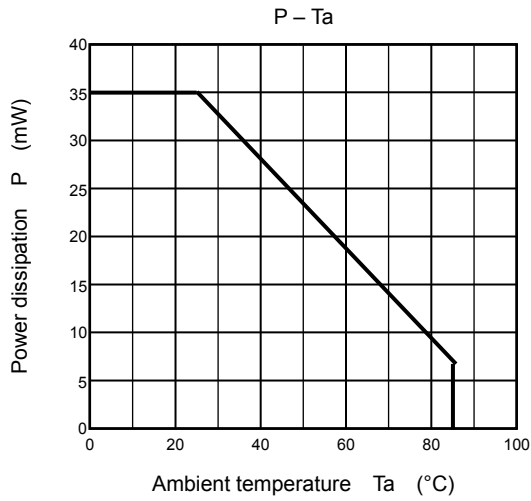
P/N

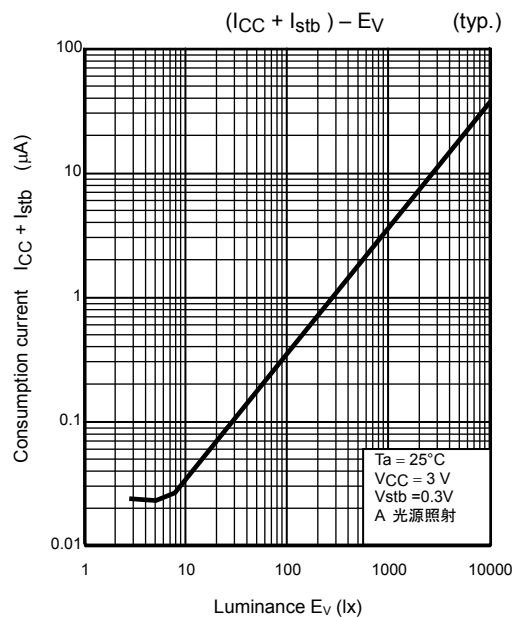
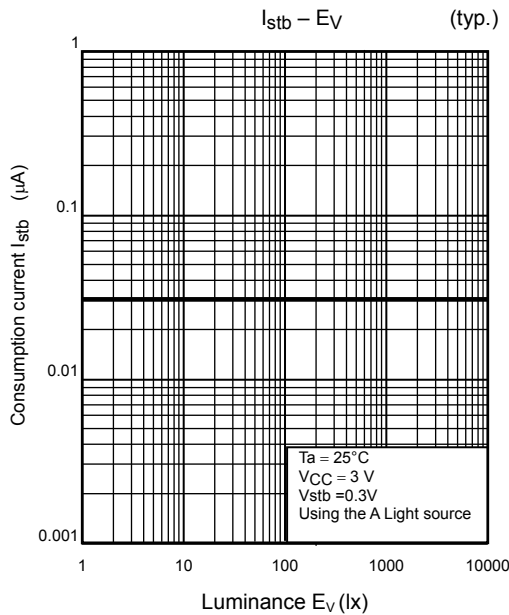
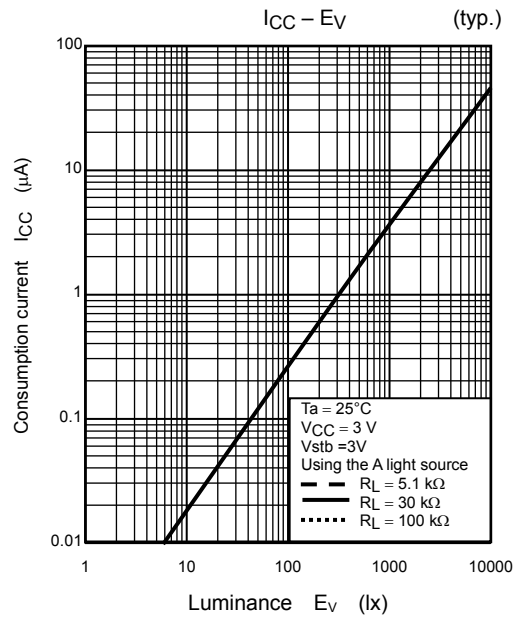
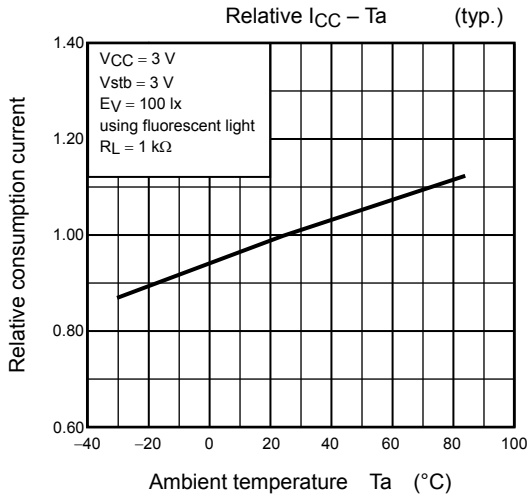
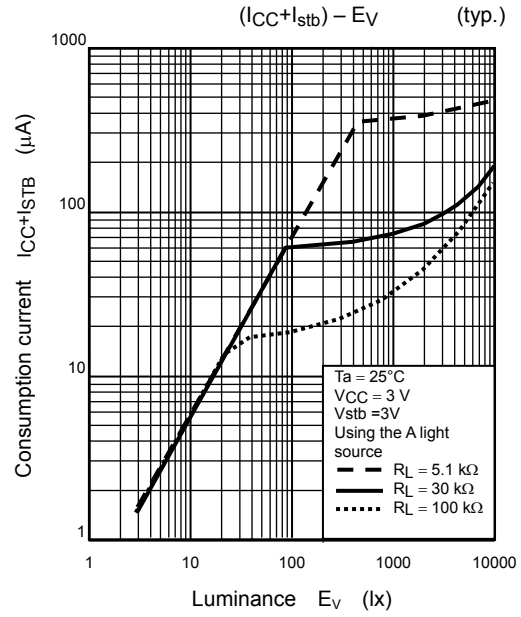
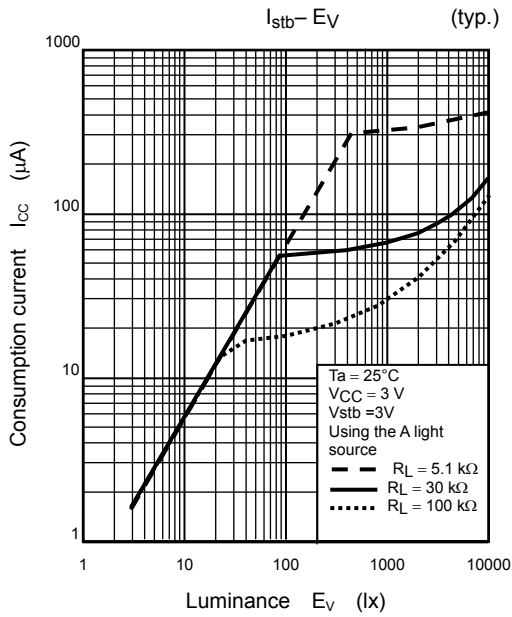
TYPE	TPS853		
ADDC		Q'TY	3,000 pcs.
NOTE			



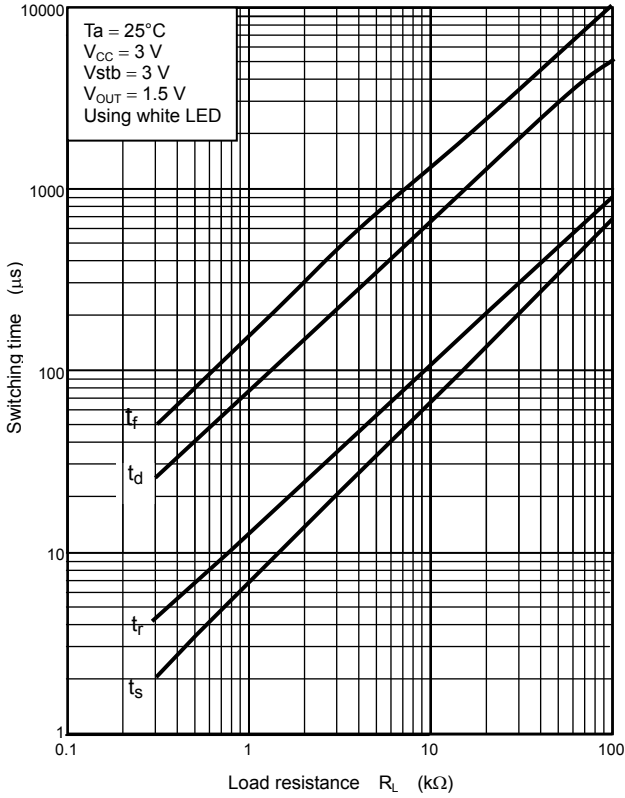
Leader and Trailer Sections of Tape



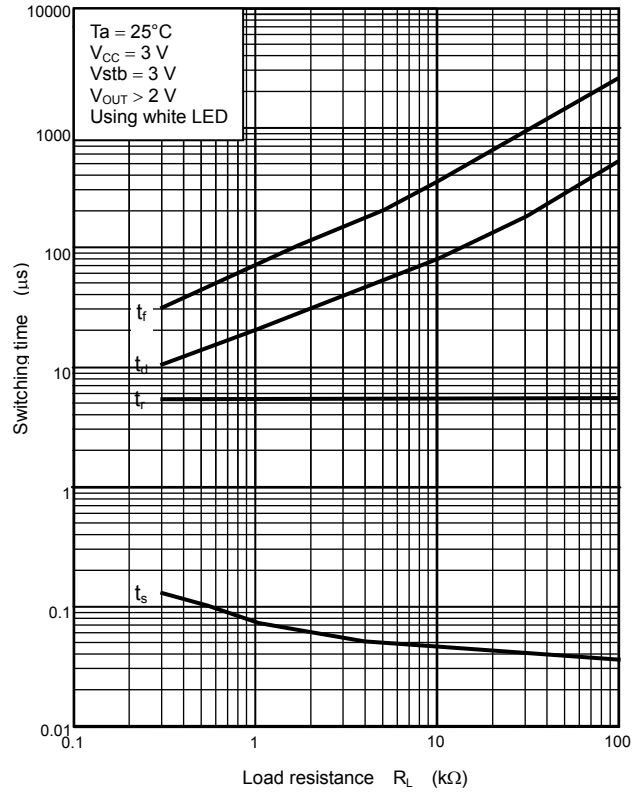




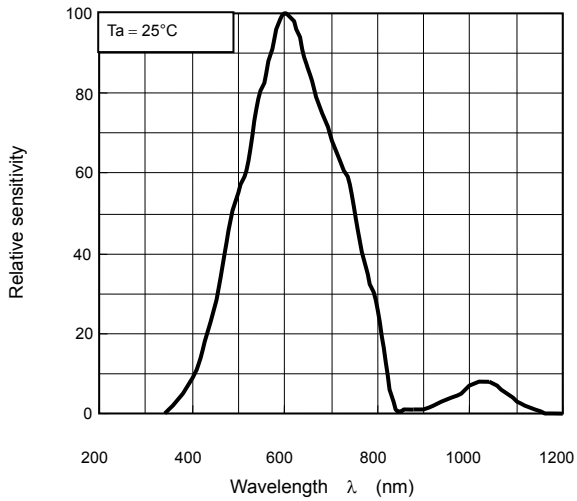
Switching Characteristics
(non-saturating operation)



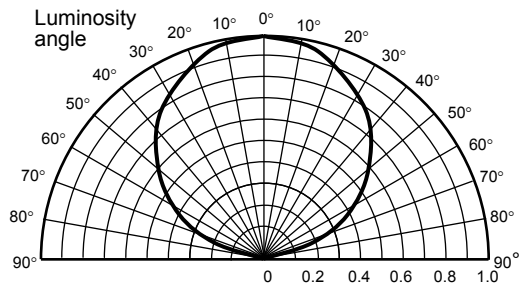
Switching Characteristics
(saturating operation)



Spectral Response (typ.)



Radiation Pattern (typ.)
 $T_a = 25^\circ\text{C}$



RESTRICTIONS ON PRODUCT USE

20070701-EN GENERAL

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